



Material Composition Declaration

EPC2108

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/22/2017
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	3.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	2.6104	87.5832	90.0845	875832
	Silicon oxide	7631-86-9	0.0118	0.3972		3972
	Silicon nitride	12033-89-5	0.0040	0.1343		1343
	Gallium nitride	25617-97-4	0.0135	0.4540		4540
	Aluminum	7429-90-5	0.0179	0.6020		6020
	Aluminum nitride	24304-00-5	0.0033	0.1091		1091
	Titanium	7440-32-6	0.0005	0.0158		158
	Titanium nitride	25583-20-4	0.0017	0.0562		562
	Copper	7440-50-8	0.0006	0.0200		200
	Tungsten	7440-33-7	0.0003	0.0087		87
	Polyimide		0.0210	0.7039		7039
Under Bump Metal	Titanium	7440-32-6	0.0002	0.0060	0.5098	60
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.0150	0.5038		5038
Solder Bump	Tin	7440-31-5	0.2677	8.9825	9.4057	89825
	Silver	7440-22-4	0.0112	0.3762		3762
	Copper	7440-50-8	0.0014	0.0470		470
Sum in total:			2.9805	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.